



Pin	Signal Name	Mating Sequence	Pin	Signal Name	Mating Sequence
A1	GND	First	B12	GND	First
A2	SSTxp1	Second	B11	SSKxp1	Second
A3	SSTIn1	Second	B10	SSKIn1	Second
A4	V _{cc}	First	B9	V _{cc}	First
A5	CL1	Second	B8	SBU2	Second
A6	Dn1	Second	B7	Dn2	Second
A7	Dn1	Second	B6	Dp2	Second
A8	SBU1	Second	B5	CL2	Second
A9	V _{cc}	First	B4	V _{cc}	First
A10	SSKIn2	Second	B3	SSTIn2	Second
A11	SSKxp2	Second	B2	SSTxp2	Second
A12	GND	First	B1	GND	First
SHELL	GND		SHELL	GND	

Material
Housing Material: High temperature thermoplastic
Contact Terminal: High Grade Copper Alloy
Metallic Shell: Stainless Steel
Cover Shell: Iron
Inner Ground Cover Shell: Stainless Steel
Mid Plate: Stainless Steel
Plating
Data Contact
Underplating: 50µ" Min. Nickel
Contact Plating: 1µ" Gold
Solder Area: 80µ" Matte Tin
Shell
Metallic Shell: 50µ" Min. Nickel
Cover Shell
Metallic Shell: 80µ" Min. Nickel
Inner Ground Cover Shell
Metallic Shell: 50µ" Min. Nickel
Electrical
Voltage Rating: 20V DC
Current Rating: Vbus pins collectively 5.00A, GND pins collectively 6.25A, B5 pin 1.25A, Other pins 0.25A per pin.
Contact Resistance: 40mΩ Max.
Insulation resistance: 100 MΩ MIN.
Dielectric withstanding voltage: 100V AC/Minute
Mechanical
Durability: 10,000 cycles
Mating Force: 5 to 20N
Unmating Force: 8 to 20N (post test)

USB31-TPPEC-32X41-XFS
1: Tray 2: Tape reel
41: IPX7
52: IP54
53: 不防水
1: G/F 2: 5u" 3: 10u"
4: 15u" 5: 30u"

MARK	DESCRIPTION	DATE	REVISED	APPROVED	UNSPECIFIED TOLERANCES	DATE	SCALE: N/A	MODEL TYPE: USB 3.1 CF WATERPROOF CL1.75 H3.46mm DIP TYPE
					ANGULAR ±5°			
△X					L ≤ 4 ±0.2		VIEW:	PART NO.:
△X					4 < L ≤ 16 ±0.3		UNIT: mm	DWG NO.:
△X					16 < L ≤ 63 ±0.4		SIZE: A4	USB31-TYPEC-32X41-XFS
					L > 63 ±0.5			WEIGHT 1.0g
								SHEET 1/1
								REVISION A0